


MULTI LAYER CERAMIC ELECTRONIC COMPONENT MANUFACTURING METHOD


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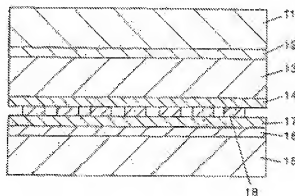
 JP3236210 (A)

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Abstract of WO 03036667 (A1)

A method comprises a first step of fabricating a multilayer body by stacking alternately ceramic sheets and internal electrodes with adhesive layers interposed therebetween and a second step of baking the multilayer body. The adhesive layers contain a thermoplastic resin and one or more kinds out of Cr, Mg, Al, Si, their compounds, and an inorganic powder constituting the ceramic sheets. By such a method, the adhesion between the baked ceramic layers and the internal electrodes is improved, and structural defects such as delamination and cracks are suppressed.



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